L Number	Hits	Search Text	DB	Time stamp
–	56117	((wafer or semiconductor or substrate) same plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 07:22
–	355	(plating near15 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:29
–	78	(((wafer or semiconductor or substrate) same plating)) and ((plating near15 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:11
–	370	(plating near25 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:12
–	79	((plating near25 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse)) and (((wafer or semiconductor or substrate) same plating))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:13
–	436	(plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:21
–	88	((plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse)) and (((wafer or semiconductor or substrate) same plating))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:17
–	1177	(plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:30
–	204	((plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and (((wafer or semiconductor or substrate) same plating))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:23
–	56117	((wafer or semiconductor or substrate or circuir) same plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:24
–	70084	((wafer or semiconductor or substrate or circuit) same plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:34
–	56117	(((wafer or semiconductor or substrate or circuit) same plating)) and (((wafer or semiconductor or substrate or circuir) same plating))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:25
–	298	(((wafer or semiconductor or substrate or circuit) same plating)) and ((plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:25

~	355	((plating or metalizing) near15 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:30
–	1187	((plating or metalizing)near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:30
–	1187	((plating or metalizing)near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:31
–	298	(((plating or metalizing)near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and (((wafer or semiconductor or substrate or circuit) same plating))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:31
–	1204	((plating or metalizing)near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:32
–	309	(((plating or metalizing)near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and (((wafer or semiconductor or substrate or circuit) same plating))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:33
–	5865	((wafer or semiconductor or substrate or circuit) same plating)	USOCR	2004/05/30 16:34
–	98	((plating or metalizing)near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USOCR	2004/05/30 16:35
–	33	(((wafer or semiconductor or substrate or circuit) same plating)) and (((plating or metalizing)near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering))	USOCR	2004/05/30 16:35
–	1204	((plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 17:21
–	2436	((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 17:21

-	31	((((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat)	USOCR	2004/05/30 17:22
-	242	((((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 06:28
-	0	(brest near10 implants) same safe	USPAT	2004/05/30 22:35
-	6	(breast near10 implants) near15 safe	USPAT	2004/05/30 22:36
-	630	breast near10 implants	USPAT	2004/05/30 22:42
-	30	"car wash" and stinson and 134/$.ccls.	USPAT	2004/05/31 03:53
-	2	("6391209").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 05:24
-	16	"4652352" and (volume or weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 05:25
-	0	"4652352" and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 05:27
-	5	((((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:31
-	0	((((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	USOCR	2004/05/31 05:32

–	7	((plating or metalizing)near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:33
–	1540	((metalizing or etching or etchant or electroplating plating) near25 (liquid or fluid or solution)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:37
–	1290	((metalizing or etching or etchant or electroplating plating) near25 (liquid or fluid or solution)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe)) and (wafer or semiconductor or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:38
–	201	((metalizing or etching or etchant or electroplating plating) near25 (liquid or fluid or solution)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe)) and (wafer or semiconductor or substrate) and (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:42
–	134	((metalizing or etching or etchant or electroplating plating)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe)) and (wafer or semiconductor or substrate) and ((regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering) near15 (liquid or fluid or solution))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:43
–	183	((metalizing or etching or etchant or electroplating plating)) and ((volume or weight) near15 (sensor or detector or monitor or measuring or measure or indicator or probe)) and (wafer or semiconductor or substrate) and ((regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering) near15 (liquid or fluid or solution))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 06:12
–	5	("6569307" or "6077437" or "6024856") and ((volume or weight) near15 (sensor or detector or monitor or measuring or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 06:25
–	8	("4252621" or "5980771" or "4652352" or "6569307" or "4042444") and heater	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 06:50
–	54	(((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat) and heater	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 06:46

–	3	"6391209" and heater	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 06:46
–	25	("4252621" or "5980771" or "4652352" or "6569307" or "4042444") and (heated or heating or heater)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 06:55
–	592	((wafer or semiconductor or substrate) same plating) and 118/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 07:23
–	1114	(wafer or semiconductor or substrate) and(electroplating or plating) and 118/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 07:27
–	99	(wafer or semiconductor or substrate) and(electroplating or plating) and 118/$.ccls.	USOCR	2004/05/31 07:29
–	497	(electroplating or plating) and 118/$.ccls.	USOCR	2004/05/31 07:29
–	8945	(electroplating or plating coating) and 118/$.ccls.	USOCR	2004/05/31 07:34
–	20422	(electroplating or plating coating) and 118/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 07:34